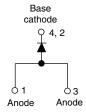


### Vishay Semiconductors

### Schottky Rectifier, 3.5 A





D-PAK	(TO-252AA)
-------	------------

PRODUCT SUMMARY						
Package	D-PAK (TO-252AA)					
I <sub>F(AV)</sub>	3.5 A					
$V_R$	100 V					
V <sub>F</sub> at I <sub>F</sub>	See Electrical table					
I <sub>RM</sub>	4.9 mA at 125 °C					
T <sub>J</sub> max.	150 °C					
Diode variation	Single die					
E <sub>AS</sub>	5 mJ					

#### **FEATURES**

- Popular D-PAK outline
- Small foot print, surface mountable



- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Compliant to RoHS Directive 2002/95/EC
- $\bullet$  Meets MSL level 1, per J-STD-020, LF maximum peak of 260  $^{\circ}\text{C}$

#### **DESCRIPTION**

The VS-30WQ10FNPbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and small foot prints on PC board. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS							
SYMBOL CHARACTERISTICS VALUES UNITS							
I <sub>F(AV)</sub>	Rectangular waveform	3.5	А				
V <sub>RRM</sub>		100	V				
I <sub>FSM</sub>	t <sub>p</sub> = 5 µs sine	440	А				
V <sub>F</sub>	3 Apk, T <sub>J</sub> = 125 °C	0.63	V				
T <sub>J</sub>		- 40 to 150	°C				

VOLTAGE RATINGS							
PARAMETER	SYMBOL	VS-30WQ10FNPbF	UNITS				
Maximum DC reverse voltage	V <sub>R</sub>	100	V				
Maximum working peak reverse voltage	$V_{RWM}$	100	V				

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST COND	ITIONS	VALUES	UNITS			
Maximum average forward current See fig. 5	I <sub>F(AV)</sub>	50 % duty cycle at T <sub>C</sub> = 135 °C	3.5					
Maximum peak one cycle non-repetitive surge current	l=a	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated	440	Α			
See fig. 7	I <sub>FSM</sub>	10 ms sine or 6 ms rect. pulse	V <sub>RRM</sub> applied	70				
Non-repetitive avalanche energy	E <sub>AS</sub>	T <sub>J</sub> = 25 °C, I <sub>AS</sub> = 1 A, L = 10 mH		5.0	mJ			
Repetitive avalanche current	I <sub>AR</sub>	Current decaying linearly to zero in 1 $\mu$ s Frequency limited by T <sub>J</sub> maximum V <sub>A</sub> = 1.5 x V <sub>B</sub> typical		0.5	А			

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# VS-30WQ10FNPbF

# Vishay Semiconductors

### Schottky Rectifier, 3.5 A



ELECTRICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST COND	ITIONS	VALUES	UNITS			
		3 A	T <sub>J</sub> = 25 °C	0.81				
Maximum forward voltage drop	V <sub>FM</sub> <sup>(1)</sup>	6 A	11 = 23 0	0.96	V			
See fig. 1	VFM \''	3 A	T <sub>J</sub> = 125 °C	0.63	V			
		6 A	1j = 125 C	0.74				
Maximum reverse leakage current	I <sub>RM</sub> <sup>(1)</sup>	T <sub>J</sub> = 25 °C	V <sub>R</sub> = Rated V <sub>R</sub>	1	mA			
See fig. 2	IRM (")	T <sub>J</sub> = 125 °C	v <sub>R</sub> = nateu v <sub>R</sub>	4.9				
Threshold voltage	V <sub>F(TO)</sub>	T - T movimum		0.48	V			
Forward slope resistance	r <sub>t</sub>	ıj = ıjınaxımum	$T_J = T_J$ maximum		mΩ			
Typical junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 5 V <sub>DC</sub> (test signal range	92	pF				
Typical series inductance	L <sub>S</sub>	Measured lead to lead 5 mm	5.0	nH				
Maximum voltage rate of change	dV/dt	Rated V <sub>R</sub>		10 000	V/µs			

#### Note

 $<sup>^{(1)}\,</sup>$  Pulse width  $<300~\mu s,$  duty cycle <2~%

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Maximum junction and storage temperature range	T <sub>J</sub> <sup>(1)</sup> , T <sub>Stg</sub>		- 40 to 150	°C					
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation See fig. 4	4.7	°C/W					
Approximate weight			0.3	g					
Approximate weight			0.01	OZ.					
Marking device		Case style D-PAK (similar to TO-252AA)	30WC	10FN					

#### Note

 $^{(1)} \quad \frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}} \quad \text{thermal runaway condition for a diode on its own heatsink}$ 



### Schottky Rectifier, 3.5 A

### Vishay Semiconductors

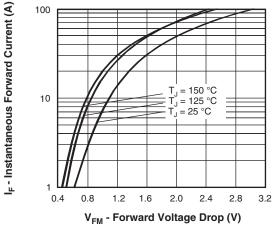


Fig. 1 - Maximum Forward Voltage Drop Characteristics

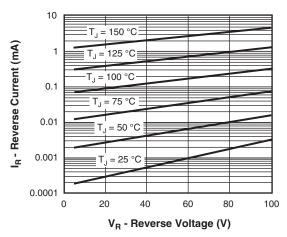


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

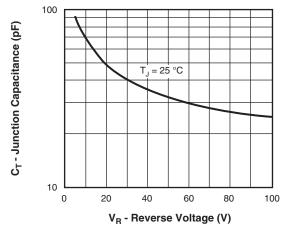


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

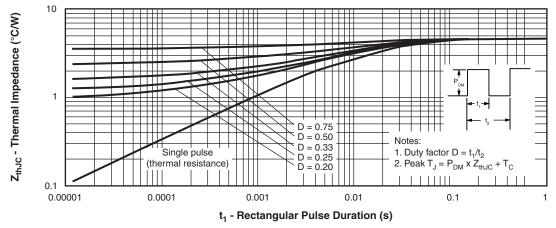
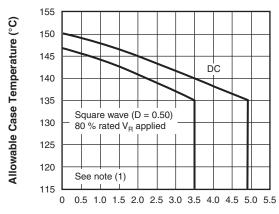


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

## Vishay Semiconductors

### Schottky Rectifier, 3.5 A





 $I_{F(AV)}$  - Average Forward Current (A)

Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

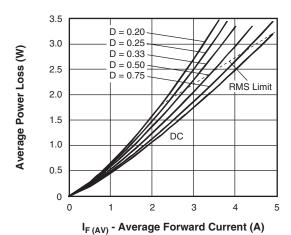


Fig. 6 - Forward Power Loss Characteristics

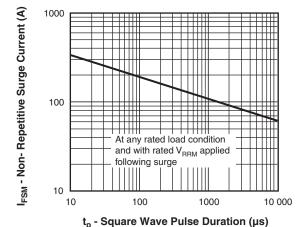


Fig. 7 - Maximum Non-Repetitive Surge Current

#### Note

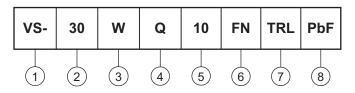
 $^{(1)}$  Formula used: T<sub>C</sub> = T<sub>J</sub> - (Pd + Pd<sub>REV</sub>) x R<sub>th,JC</sub>; Pd = Forward power loss = I<sub>F(AV)</sub> x V<sub>FM</sub> at (I<sub>F(AV)</sub>/D) (see fig. 6); Pd<sub>REV</sub> = Inverse power loss = V<sub>R1</sub> x I<sub>R</sub> (1 - D); I<sub>R</sub> at V<sub>R1</sub> = 80 % rated V<sub>R</sub>

Schottky Rectifier, 3.5 A

Vishay Semiconductors

#### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

Current rating (3.5 A)

Package identifier:

W = D-PAK

4 - Schottky "Q" series

5 - Voltage rating (10 = 100 V)

6 - FN = TO-252AA (D-PAK)

7 - • None = Tube (50 pieces)

• TR = Tape and reel

• TRL = Tape and reel (left oriented)

• TRR = Tape and reel (right oriented)

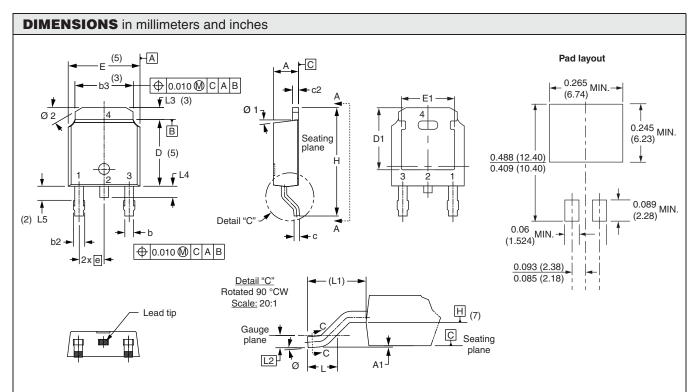
PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95016</u>					
Part marking information	www.vishay.com/doc?95059				
Packaging information	www.vishay.com/doc?95033				



### Vishay High Power Products

## **D-PAK (TO-252AA)**



SYMBOL	MILLIMETERS		INC	NOTES	
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIM	MILLIMETERS		INCHES		
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
е	2.29	BSC	0.090	BSC		
Н	9.40	10.41	0.370	0.410		
L	1.40	1.78	0.055	0.070		
L1	2.74	BSC	0.108	REF.		
L2	0.51	BSC	0.020 BSC			
L3	0.89	1.27	0.035	0.050	3	
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060	2	
Ø	0°	10°	0°	10°		
Ø1	0°	15°	0°	15°		
Ø2	25°	35°	25°	35°		

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- $^{(7)}$  Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA

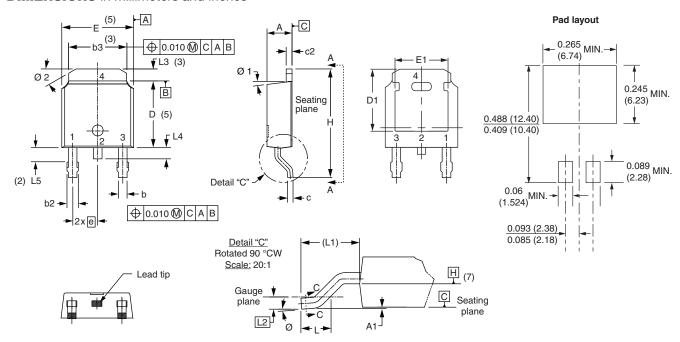
Document Number: 95016 Revision: 04-Nov-08



## Vishay Semiconductors

## **D-PAK (TO-252AA)**

#### **DIMENSIONS** in millimeters and inches



	SYMBOL	MILLIN	MILLIMETERS		INCHES		SYMBOL	MILLIMETE	
		MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STIVIDUL	MIN.
	А	2.18	2.39	0.086	0.094		е	2.29	BSC
	A1	-	0.13	-	0.005		Н	9.40	10
	b	0.64	0.89	0.025	0.035		L	1.40	1.
	b2	0.76	1.14	0.030	0.045		L1	2.74	BSC
	b3	4.95	5.46	0.195	0.215	3	L2	0.51	BSC
	С	0.46	0.61	0.018	0.024		L3	0.89	1.
	c2	0.46	0.89	0.018	0.035		L4	-	1.
	D	5.97	6.22	0.235	0.245	5	L5	1.14	1.
	D1	5.21	-	0.205	-	3	Ø	0°	1
	E	6.35	6.73	0.250	0.265	5	Ø1	0°	1
	E1	4.32	-	0.170	-	3	Ø2	25°	3

SYMBOL	MILLIN	MILLIMETERS		HES	NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	
е	2.29	BSC	0.090	BSC		
Н	9.40	10.41	0.370	0.410		
L	1.40	1.78	0.055	0.070		
L1	2.74	BSC	0.108	0.108 REF.		
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- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA



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